MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TSSOP48 12.5x6.1
CASE 948BQ
ISSUE O

DATE 30 SEP 2016

DIMENSIONS ARE IN MILLIMETERS

NOTES:
A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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